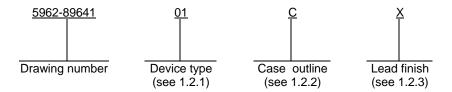
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А	Changes in	n accord	lance w	ith N.C).R. 59	62-R03	5-93.			93-03-18			M. A. FRYE						
В	Changes in accordance with N.O.R. 5962-R176-96.						94-01-03			M. A. FRYE									
С	Drawing updated to reflect current requirementsro								01-0	04-11			R M	ONNIN					
D	Update drawing as part of 5 year reviewrrp										07-11		RC	R. MONNIN ROBERT M. HEBER					
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PMIC N/A	PMIC N/A PREPARED BY RICK C. OFFICER STANDARD CHECKED BY			DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990															
	CIRCUIT WING	•	С	HARLE	S E. E	SESOR	E					http)://wv	vw.ds	cc.dl	lla.mil			
THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS		ABLE	APPROVED BY MICHAEL A. FRYE				MICROCIRCUIT, LINEAR, FAST SETTLING, UNITY-GAIN STABLE, OPERATIONAL AMPLIFIER MONOLITHIC SILICON					IER,							
	AND AGENCIES OF THE DEPARTMENT OF DEFENSE DRAWING APPROVAL DATE 92-07-07																		
AMS	SC N/A		REV	ISION		D				ZE A		GE CC			;	5962-	8964	11	
									SHE	ET	•	1	I OF	11					

1. SCOPE

- 1.1 <u>Scope</u>. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.
 - 1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:



1.2.1 Device type(s). The device type(s) identify the circuit function as follows:

 Device type
 Generic number
 Circuit function

 01
 AD841
 Unity-gain stable, fast settling operational amplifier

1.2.2 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
С	GDIP1-T14 or CDIP2-T14	14	Dual-in-line
Χ	See figure 1	12	Can
2	CQCC1-N20	20	Square leadless chip carrier

- 1.2.3 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.
- 1.3 Absolute maximum ratings. 1/ 2/

Voltage between +Vs and -Vs terminals	36 V dc
Differential input voltage	±6.0 V dc
Voltage at either input terminal	$+V_S$ and $-V_S$
Peak output current (< 10 % duty cycle)	100 mA
Power dissipation (P _D):	
Case C	
Case X	
Case 2	1.0 W <u>3</u> /
Junction temperature (T _J)	+175°C
Storage temperature range	-65°C to +150°C
Lead temperature (soldering, 10 seconds)	+300°C
Thermal resistance, junction-to-case (θ_{JC}):	
Cases C and X	30°C/W
Case 2	35°C/W
Thermal resistance, junction-to-case (θ_{JA}):	
Case C	110°C/W
Case X	100°C/W
Case 2	150°C/W

- 1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.
- 2/ Unless otherwise specified, $T_A = +25$ °C.
- 3/ Derate linearly above $T_A = +25^{\circ}C$ for case C at 8.7mw/°C, case X at 10 mW/°C and case 2 at 6.7 mW/°C.

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1.4 Recommended operating conditions.

2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at http://assist.daps.dla.mil or http://assist.daps.dla.mil/quicksearch/ or <a href="http://assist.daps.dla.mil/

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.
 - 3.2.1 Case outline. The case outline shall be in accordance with 1.2.2 herein and figure 1.
 - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full ambient operating temperature range.

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- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.
- 3.5.1 <u>Certification/compliance mark</u>. A compliance indicator "C" shall be marked on all non-JAN devices built in compliance to MIL-PRF-38535, appendix A. The compliance indicator "C" shall be replaced with a "Q" or "QML" certification mark in accordance with MIL-PRF-38535 to identify when the QML flow option is used.
- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.
 - 3.8 Notification of change. Notification of change to DSCC-VA shall be required for any change that affects this drawing.
- 3.9 <u>Verification and review</u>. DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

4. VERIFICATION

- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 <u>Quality conformance inspection</u>. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
 - 4.3.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 7 and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.

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		TABLE I. Electrical performance	e characteristic	<u>s</u> .			
Test	Symbol	Conditions $\underline{1}/$ -55°C \leq T _A \leq +125°C \pm V _S = \pm 15 V	Group A subgroups	Device type		ts <u>2</u> /	Unit
lanut offest volteres		unless otherwise specified	1	01	Min	Max	mV
Input offset voltage	V _{IO}	V _{CM} = 0 V		01	-2.0	+2.0	IIIV
			2,3		-5.5	+5.5	
Input bias current	+l _B	V _{CM} = 0 V	1	01		+8	μА
			2,3	=		+12	
	-I _B		1			+8	
			2,3	-		+12	
Input offset current	I _{IO}	V _{CM} = 0 V	1	01	-0.4	+0.4	μΑ
			2,3	-	-0.6	+0.6	
Common mode voltage	+V _{CM}	+V _S = 5.0 V, -V _S = -25 V	1,2,3	01	10		V
range		V _{OUT} = -10 V					
	-V _{CM}	+V _S = 25 V, -V _S = -5 V	1			-10	
		V _{OUT} = 10 V					
Large signal voltage gain	+A _{VOL}	V _{OUT} = 0 V and 10 V,	1	01	25		V/mV
3		R _L = 500 Ω	2,3		12		
	-A _{VOL}	V _{OUT} = 0 V and -10 V,	1		25		
		R _L = 500 Ω	2,3	=	12		
Output current	+lout	V _{OUT} = 0 V, T _A = +25°C	1	01	50		mA
	-lout	V _{OUT} = 0 V, T _A = +25°C				-50	
Output voltage swing	+Vout	R _L = 500 Ω	1,2,3	01	10		V
	-Vout					-10	
Quiescent power supply current	+lcc	V _{OUT} = 0 V, I _{OUT} = 0 mA	1	01		+12	mA
Sarrom			2,3	1		+16	
	-I _{CC}		1	1	-12		
			2,3	1	-16		
		ļ	ļ	į			1

See footnotes at end of table.

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Test	Symbol	Conditions $\underline{1}/$ -55°C \leq T _A \leq +125°C \pm V _S $=$ \pm 15 V	Group A subgroups	Device type	Limi	ts <u>2</u> /	Unit
		unless otherwise specified			Min	Max	
Power supply rejection ratio	+PSRR	$+V_S = 5.0 \text{ V to } 18 \text{ V},$	1	01	86		dB
		-V _S = -15 V	2,3		80		
	-PSRR	-V _S = -5.0 V to -18 V	1		86		
		+V _S = +15 V	2,3	•	80		
Quiescent power <u>3</u> / consumption	PC	V _{OUT} = 0 V, I _{OUT} = 0 mA	1	01		360	mW
condamption			2,3	-		480	0
Common mode rejection ratio	+CMRR	$\Delta V_{CM} = 10 \text{ V}, +V_{S} = 5.0 \text{ V},$	1	01	86		dB
Tallo		-V _S = -25 V, V _{OUT} = -10 V	2,3		80		
	-CMRR	$\Delta V_{CM} = -10 \text{ V}, +V_{S} = 25 \text{ V},$	1		86		
		-V _S = -5 V, V _{OUT} = 10 V	2,3		80		
Differential input 4/ resistance	R _{IN}	V _{CM} = 0 V, T _A = +25°C	4	01	65		kΩ
Gain bandwidth <u>4</u> / product	GBWP	V _{OUT} = ±100 mV,	4	01	23		MHz
product		f ₁ = 100 kHz, f ₂ = 10 MHz,					
		$R_L = 500 \Omega, T_A = +25^{\circ}C$					
Full power <u>4</u> / <u>5</u> / bandwidth	FPBW	$V_{PK} = 10 \text{ V}, R_L = 500 \Omega,$	4	01	3.1		MHz
Dandwidth		T _A = +25°C					
Closed loop stable 4/ gain	CLSG	$R_L = 500~\Omega,~C_L \leq 10~pF$	4,5,6	01	1		V/V
Slew rate 4/	+SR	V _{OUT} = -5.0 V to 5.0 V, measured from 10 % to	9	01	220		V/µs
	1	90 % point, $R_L = 500 \Omega$,	10,11	1	140		1

See footnotes at end of table.

-SR

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220

140

9

10,11

 $A_V = -1 \text{ V/V}$, rising edge

 $V_{OUT} = 5.0 \text{ V to } -5.0 \text{ V},$ measured from 90 % to

10 % point, R_L = 500 Ω , A_V = -1 V/V, falling edge

TABLE I. <u>Electrical performance characteristics</u> – Continued.

Test	Symbol	Conditions $\underline{1}/$ -55°C \leq T _A \leq +125°C \pm V _S = \pm 15 V	Group A subgroups	Device type	Limi	ts <u>2</u> /	Unit
		unless otherwise specified			Min	Max	
Rise time <u>4/ 6/</u>	t _R	$V_{OUT} = 0 V \text{ to } +200 \text{ mV},$	9,10,11	01		10	ns
		$A_V = +1, R_L = 500 \Omega,$					
Fall time <u>4/ 6</u> /	tF	$V_{OUT} = 0 \text{ V to -200 mV},$	9,10,11	01		10	ns
		$A_V = +1, R_L = 500 \Omega,$					
Settling time 4/	ts	A _V = -1 V/V, R _L = 500 Ω , 10 V step at 0.1 % of the fixed value, T _A = +25°C	9	01		150	ns
		A _V = -1 V/V, R _L = 500 Ω , 10 V step at 0.01 % of the fixed value, T _A = +25°C				200	
Overshoot <u>4</u> /	+0\$	V_{OUT} = 0 V to +200 mV, A_V = +1, R_L = 500 Ω , T_A = +25°C	9	01		40	%
	-OS	$V_{OUT} = 0 \text{ V to -200 mV},$ $A_{V} = +1, R_{L} = 500 \Omega,$ $T_{A} = +25^{\circ}\text{C}$				40	

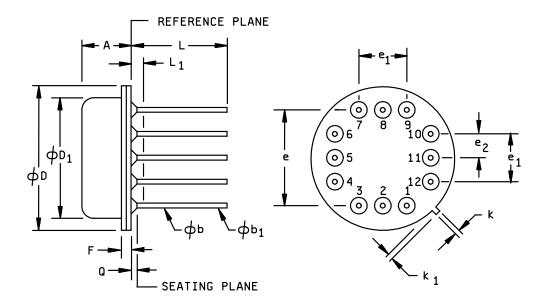
- 1/ Unless otherwise specified, for dc tests, $R_L = 100 \text{ k}\Omega$ and $V_{OUT} = 0 \text{ V}$.
- 2/ The algebraic convention, whereby the most negative value is a minimum and the most positive is a maximum, is used in this table. Negative current shall be defined as conventional current flow out of device terminal.
- 3/ Quiescent power consumption is based on quiescent supply current test maximum with no load on outputs.
- 4/ If not tested, shall be guaranteed to the limits specified in table I herein.
- 5/ Full power bandwidth = SR / ($2\pi \times V_{PK}$).
- 6/ Rise and fall times measured between 10 percent and 90 percent point.

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MICROCIRCUIT DRAWING

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Case outline X



Symbol	Inches		Millim	eters	Notes
	Min	Max	Min	Max	
Α	.148	.181	3.76	4.60	
фЬ	.016	.019	0.41	0.48	1
φb1	.016	.021	0.41	0.53	1
φD	.592	.615	15.04	15.62	
φD1	.545	.555	13.84	14.10	
е	.400 BSC		10.16	BSC	3
e1	.200 BSC		5.00	BSC	3
e2	.100	.100 BSC		BSC	3
F		.040		1.02	
k	.026	.036	0.66	0.91	
k1	.027	.037	0.68	0.94	2
L	.375		9.50		
L1		.050		1.27	1
Q	.010	.045	0.25	1.14	

NOTES:

- 1. All leads ϕ b applies between L and L₁. ϕ b1 applies between L₁ and .375 inch (9.52 mm) from the reference plane.
- 2. Measured from the maximum diameter of the product.
- 3. Leads having a maximum diameter .019 inch (0.48 mm) measured in gauging plane .054 inch (1.37 mm) + .001 inch (0.03 mm) .000 inch (0.000 mm) below the base plane of the product are within .007 inch (0.18 mm) of their true position relative to the maximum width tab.

FIGURE 1. Case outline.

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01			
С	2		
Terminal symbol			
NC	NC	NC	
NC	NC	BALANCE	
BALANCE	BALANCE	NC	
-INPUT	BALANCE	NC	
+INPUT	-INPUT	-INPUT	
-V _S	+INPUT	NC	
NC	NC	+INPUT	
NC	NC	NC	
NC	NC	NC	
OUTPUT	-V _S	-Vs	
+V _S	OUTPUT	NC	
BALANCE	+V _S	NC	
NC		NC	
NC		NC	
		OUTPUT	
		NC	
		+V _S	
		NC	
		NC	
		BALANCE	
	NC NC BALANCE -INPUT +INPUT -Vs NC NC NC OUTPUT +Vs BALANCE NC NC	C X Terminal symbol NC NC NC NC BALANCE BALANCE -INPUT BALANCE +INPUT -INPUT NC NC NC NC NC NC OUTPUT -Vs +Vs OUTPUT BALANCE +Vs NC NC <	

NC = No connection

FIGURE 2. <u>Terminal connections</u>.

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	1,4
Final electrical test parameters (method 5004)	1*,2,3,4,
Group A test requirements (method 5005)	1,2,3,4**,5**,6**,9**,10**,11**
Groups C and D end-point electrical parameters (method 5005)	1

^{*} PDA applies to subgroup 1.

4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

5. PACKAGING

- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.
- 6. NOTES
- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

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^{**} Subgroups 4, 5, 6, 9, 10, and 11, if not tested, shall be guaranteed to the limits specified in table I herein.

6.4 Record of users. Military and industrial users shall inform application requires configuration control and the applicable SN used for coordination and distribution of changes to the drawing 5962) should contact DSCC-VA, telephone (614) 692-0544.	ID. DSCC will ma	intain a record of users and	this list will be
6.5 <u>Comments</u> . Comments on this drawing should be directed (614) 692-0547	ed to DSCC-VA, C	Columbus, Ohio 43218-3990), or telephone
6.6 <u>Approved sources of supply</u> . Approved sources of suppl HDBK-103 have agreed to this drawing and a certificate of com DSCC-VA.			
		1	1
STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS	SIZE A		5962-89641
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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 07-07-11

Approved sources of supply for SMD 5962-89641 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DSCC maintains an online database of all current sources of supply at http://www.dscc.dla.mil/Programs/Smcr/.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962-8964101CA	24355	AD841SQ/883B
5962-8964101XA	<u>3</u> /	AD841SH/883B
5962-89641012A	24355	AD841SE/883B

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source of supply.

Vendor CAGEVendor namenumberand address

24355 Analog Devices

Route 1 Industrial Park P.O. Box 9106 Norwood, MA 02062

Point of contact: 804 Woburn Street

Wilmington, MA 01887-3462

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.